

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

QFN 4mm X 4mm Exp. Pad

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**TOTAL MASS (g) : 0.038662**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000868	1000000	22451.1640625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.015239	975000	394162.78125		
		Iron (Fe)	7439-89-6	0.000375	24000	9699.5234375		
		Phosphorus (P)	7723-14-0	0.000005	300	129.326980591		
		Zinc (Zn)	7440-66-6	0.000011	700	284.519378662		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.015630</b>	<b>1000000</b>	<b>404276.125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000734	1000000	18977.2480469		
		<b>External Plating Total:</b>				<b>0.000734</b>	<b>1000000</b>	<b>18977.2480469</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000347	1000000	8975.29296875		
<b>Internal Plating Total:</b>				<b>0.000347</b>	<b>1000000</b>	<b>8975.29296875</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000520	750000	13450.0058594		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000173	250000	4474.71337891		
<b>Die Attach Total:</b>				<b>0.000693</b>	<b>1000000</b>	<b>17924.71875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.002640	130000	68284.6484375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.017467	860000	451790.875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000203	10000	5250.67578125		
		<b>Encapsulation Total:</b>				<b>0.020310</b>	<b>1000000</b>	<b>525326.1875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000080	1000000	2069.23168945		
					<b>TOTAL MASS (g) :</b>	<b>0.038662</b>		